G363-SR0-LAX1

HPC/AI Server - 3U DP HGX H100 4-GPU DLC

Features

- Supports Liquid cooling NVIDIA HGX™ H100 4-GPU
- Supports NVIDIA® NVLink™ technology
- Up to 300GB/s GPU to GPU interconnection
- 4th Gen Intel® Xeon® Scalable Processors
- Intel® Xeon® CPU Max Series
- Dual processor, LGA 4677
- 8-Channel RDIMM DDR5 per processor, 16 x DIMMs
- Dual ROM Architecture
- 2 x 1Gb/s LAN & 2 x 10Gb/s BASE-T LAN ports
- 1 x Dedicated management port
- 8 x 2.5” Gen5 NVMe/SATA/SAS hot-swappable bays
- 1 x M.2 slot with PCIe Gen4 x4 interface
- 6 x LP PCIe Gen5 x16 slots
- 2+1 3000W 80 PLUS Titanium redundant power supplies

Specification

Dimensions
3U (W448 x H130 x D800 mm)

Motherboard
MS63-HD2

CPU
4th Generation Intel® Xeon® Scalable Processors
Intel® Xeon® CPU Max Series
CPU TDP up to 350W

Socket
2 x LGA 4677 (Socket E)

Chipset
Intel® C741 Chipset

Memory
8-Channel DDR5 memory, 16 x DIMM slots
RDIMM modules up to 96GB supported
3DS RDIMM modules up to 256GB supported
Memory speed: Up to 4800 MHz

LAN
Front side: 2 x 1Gb/s LAN ports (Intel® I350-AM2)*
1 x 10/100/1000 management LAN
Rear side: 2 x 10Gb/s BASE-T LAN ports (Broadcom® BCM57416)*
1 x 10/100/1000 management LAN (optional)
*Support NCBI function (by switch setting)

Video
Integrated in Aspeed AST2600
2D Video Graphic Adapter with PCIe bus interface
1920×1200@60Hz 32bpp, DDR4 SDRAM

Storage
8 x 2.5” Gen5 NVMe/SATA/SAS hot-swappable HDD/SSD bays
SAS card is required for SAS devices support

RAID
Intel® SATA RAID 0/1/10/5

Expansion Slots
4 x SXM5 sockets for NVIDIA HGX™ H100 4-GPU 80GB module
6 x PCIe Gen5 x16 low-profile slots
1 x M.2 slot (M-key, PCIe Gen4 x4, support 2280/22110 card)

Front I/O
2 x USB 3.2 Gen1, 1 x mini-DP, 2 x RJ45, 1 x MLAN (default)

Rear I/O
2 x RJ45, 1 x MLAN (optional)

Backplane I/O
PCIe Gen5 x4 or SATA 6Gb/s or SAS 12Gb/s

TPM
1 x TPM header with SPI interface (Optional TPM2.0 kit: CTM010)

Power Supply
2+1 3000W 80 PLUS Titanium redundant power supplies
AC Input: 115-240V

System Management
Aspeed® AST2600 management controller
GIGABYTE Management Console (AMI MegaRAC SP-X)

OS Compatibility
Windows Server 2019 / 2022
RHEL 8.6 / 8.7 / 9.0 / 9.1 / 9.2 (x64)
SLES 15 SP4
Ubuntu 22.04 / 22.04.1 / 22.04.2 / 22.04.3 LTS (x64)
VMware ESXi 7.0 Update 3i / 8.0 / 8.0 Update 1
Citrix Hypervisor 8.2 LTSC CU1

System Fans
4 x 80x80x80mm (17,000rpm)

Operating Properties
Operating temperature: 10°C to 40°C
Operating humidity: 8-80% (non-condensing)
Non-operating temperature: -40°C to 60°C
Non-operating humidity: 20%-95% (non-condensing)

Packaging Content
1 x G363-SR0, 1 x Liquid cooling kit, 6 x Carrier clips, 1 x Mini-DP to D-Sub cable, 1 x L-shape Rail kit

Reference Numbers
Barebone w/ Nvidia module: 6NG363SR0DR000LAX1*
Barebone w/ Nvidia module (RoT): 6NG363SR0MR000LAX1*
- L-shape Rail kit: 25HB2-A86102-K0R
- CPU liquid cooling kit: 25ST7-100006-C4R
- GPU liquid cooling kit: 25ST7-3000Z2-C4R
- Power supply: 25EP0-23000A-D0S
- C19 power cord 125V/15A (US): 25CP1-018000-Q0R (optional)
- C19 power cord 250V/16A (EU): 25CP3-018300-Q0R (optional)

Learn more about GIGABYTE server, visit https://www.gigacomputing.com

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